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Part Number:

0737691200

Status:

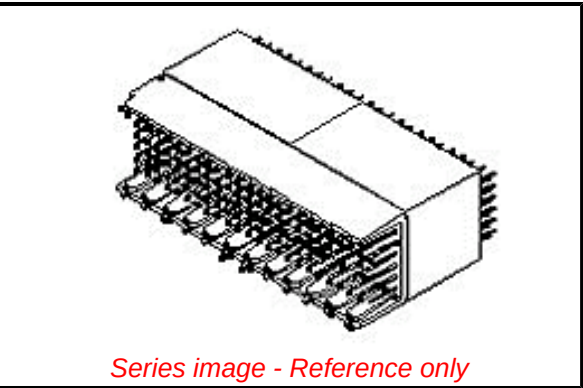
Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Stacking Header, High Rise Vertical, Press-Fit, Open End Option, 144 Circuits, Stack Height 6.05mm



Series image - Reference only

Documents:

[3D Model](#)

[Drawing \(PDF\)](#)

[Product Specification PS-73780-999-001 \(PDF\)](#)

[Packaging Specification PK-70873-0875 \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)

General	
Product Family	Backplane Connectors
Series	73769
Application	Backplane, Mezzanine
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800754835596
Physical	
Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	13.233/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.40mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole - Compliant Pin
Electrical	
Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	100V AC

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

Green Image

REACH SVHC

Not Contained Per - ED/71/2019 (16 July 2019)

Halogen-Free

Low-Halogen

Status

For more information, please visit [Contact US](#)

China ROHS

ELV

RoHS Phthalates

Green Image

Not Relevant

Not Contained

Search Parts in this Series

73769 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description

Product #

Backplane Insertion Head for 144 Circuits

622005703

Solder Process Data

Lead-freeProcess Capability	N/A
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Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0875
Product Specification	PS-73780-999-001

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